DEPARTMENT OF DEFENSE
UNITED STATES OF AMERICA

DEFENSE LOGISTICS AGENCY
LAND AND MARITIME
P.O. BOX 3990
COLUMBUS, OHIO 43218-3990

August 5, 2025

Ms. Danielle Mattox
Senior Quality Engineer
Micross
1810 South Orange Blossom Trail
Apopka, Florida 32703-9419

Dear Ms. Mattox:

Re: Notification of Qualification, Hybrid Microcircuits, MIL-PRF-38534, FSC 5962, VQ(VQH-25-039558), CN 091804

Micross at the above address is qualified to manufacture hybrid microcircuits using the processes and materials demonstrated by test report 38534-7248-25, effective May 1, 2025, under the current issue of the performance specification MIL-PRF-38534, Hybrid Microcircuits, FSC 5962.

The materials and processes qualified by this report are identified in your Hybrid Product Baseline (VQH-42H), dated December 19, 2024. Your new QML listing is Enclosure 1.

Your retention reporting period is unchanged.

If you have any questions, please contact Ms. Jonnie Schneider at (614) 692-1766.

Sincerely,

ADAMS.MICHAEL.S.1230230427
Digitally signed by ADAMS.MICHAEL.S.1230230427
Date: 2025.08.05 13:15:54 -04'00'

Michael S. Adams
Chief
Hybrid Devices Branch

Enclosures
1 QML Listing
2 Conditions Regarding Qualification Approval

Enclosure 1

QML Listing

Company Level Information

Micross (CAGE Code: 57300)
1810 South Orange Blossom Trail, Apopka, FL, 32703-9419

Company Contact: Ms. Danielle Mattox, Phone: 407-822-6307, Fax:
Land and Maritime Contact: Phone: 614-692-1766, Fax: 614-693-1658, Email: vqh.jms@dla.mil

Quality Management (QM) Program: TRB
Periodic Inspection System: Option 1
ISO 9000 System:

Technologies: Memory, DC/DC Converters

Class Level Information See Note 6/

Classes: Class H, Class E
Qualification Letters: VQ(VQH-24-038467), VQ(VQH-25-039558)

Substrate Fabrication Information See Note 1/

Substrate Fabrication Flows: MCO-Q-1-2
Substrate Fabrication: Purchased ceramic co-fire. Direct bond copper substrates, ceramic and BeO thick film substrates provided by San Jose facility.

Assembly Information See Note 1/

Assembly Flows: MCO-Q-102
Substrate Attach: Conductive epoxy, nonconductive epoxy, solder
Element Attach: Conductive epoxy, nonconductive epoxy, solder, eutectic, RTV, elastomer
Add-on Elements: Unpackaged die, tantalum capacitors, chip capacitors, inductors, transformers, stacked capacitors, tabs, flex circuits, copper wires, terminals, chip resistors
Wire Bonding: Gold, aluminum

Package Information See Note 1/ 2/ 3/

Packages: Ceramic co-fire package, pin grid array, seam weld, 4.30 seal perimeter, 66 leads, gold lead finish; metal package, axial leads, 8.0 seal perimeter, 12 leads, gold lead finish

Notes

1/ The QML listing can be expanded provided appropriate qualification testing is performed and passed. Therefore, the manufacturer may accept an order for compliant product not covered by this QML listing, but shall not ship the compliant product until the testing has been successfully completed.
2/ Package seal perimeter is listed by largest perimeter successfully tested in inches.
3/ Package lead counts are listed by maximum number of leads covered by qualification.
6/ Class E devices are devices which meet all requirements of one of the other classes (K, H, or G) with some exceptions taken. Therefore, any manufacturer qualified to G, H, or K is eligible to produce and mark product as compliant to class E.

Enclosure 2

Conditions Regarding Qualification Approval

1. A listing on the Qualified Manufacturer's List (QML) does not guarantee acceptance of the product(s) in any future purchase.

2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.

3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.

4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.

5. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

6. Continued qualification listing is dependent upon the manufacturer's compliance with the retention of qualification, verification of qualification, to which these products are qualified.